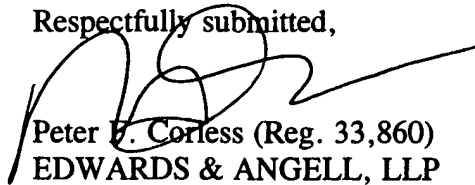


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Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Peter F. Corless', with a long horizontal line extending to the right.

Peter F. Corless (Reg. 33,860)

EDWARDS & ANGELL, LLP

Dike, Bronstein, Roberts & Cushman IP Group

P. O. Box 9169

Boston, MA 02209

(617) 439-4444



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3. (amended) The method of claim 1 [or 2] wherein multiple incorporated polymerization reagents are reacted, and the incorporated polymerization reagent with the second fastest reaction rate relative to the other incorporated polymerization reagents is added to the reaction mixture over the substantial course of the polymerization reaction.
4. (amended) The method of claim 1 [any one of claims 1 through 3] wherein multiple incorporated polymerization reagents are reacted, and the incorporated polymerization reagent with the slowest reaction rate relative to the other incorporated polymerization reagents is present in the reaction mixture at the start of the polymerization reaction and is not added to the reaction mixture over the substantial course of the polymerization reaction.
5. The method of claim 1 [any one of claims 1 through 4] wherein maleic anhydride is added to the reaction mixture over the substantial course of the polymerization reaction.
6. The method of claim 1 [any one of claims 1 through 5] wherein an acrylate compound is added to the reaction mixture over the substantial course of the polymerization reaction.
39. (amended) The method of claim 1 [any one of claims 1 through 38] further comprising applying a coating layer of the photoresist composition on a substrate, exposing the photoresist coating layer to patterned activating radiation; and developing the exposed photoresist coating layer to provide a resist relief image.

82. (amended) A method of forming a photoresist relief image, comprising:
- (a) applying a coating layer of a photoresist of claim 44 [any one of claims 44 through 81] on a substrate; and
 - (b) exposing and developing the photoresist layer to yield a relief image.

86. (amended) An article of manufacture comprising a microelectronic wafer substrate or flat panel display substrate having coated thereon a layer of the photoresist composition of claim 44 [any one of claims 44 through 81].

123. (amended) A polymer obtained by a method of claim 88 [any one of claims 88 through 122].